



February 9, 2017

Kulicke & Soffa to Participate at IPC APEX EXPO 2017

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the IPC APEX EXPO 2017 trade show from February 14 to 16, 2017.

Kulicke & Soffa will be showcasing its market leading packaging solutions at San Diego Convention Center, Booth Number 3422.

- ▮ **Asterion™** - a single platform hybrid wedge bonder™ with the capability to handle a multitude of interconnect materials including large and small aluminum wire, copper wire, *PowerRibbon™*, as well as aluminum copper-clad ribbon. In addition, the Asterion's interconnect bonding technology has recently been extended to battery applications
- ▮ **Hybrid** - a multi-application solution for advanced packaging, ideal for Wafer Level Packaging (WLP), Fan-Out Wafer Level Packaging (FOWLP), System-in-Package (SiP), Multi-Chip Module (MCM), flip-chip, modules and embedded components.
- ▮ **iFlex** - its new design features an increase in feeder capacity, achieving 25% more feeder positions. Combining this increased feeder capacity, with the high volume and high quality iX system delivers the Flexline, which offers flexibility, fast changeovers, lower cost-of-ownership and the lowest defect rates. The iFlex H1 is now available with a different placement head for placing components up to 50mm in height over pre-mounted components of 50mm.
- ▮ **Industry 4.0** - factory connectivity solution, via intelligent monitoring systems, latest technology traceability, material management and scheduling intelligence across our current and future platforms.

Chan Pin Chong, Kulicke & Soffa's Senior Vice President for AP-Hybrid, Electronics Assembly, Wedge Bonders, Capillaries and Blades Business Lines, said, "The IPC APEX EXPO has always been a valuable platform for us to connect with our partners in the Americas. We look forward to sharing how our wire bonding, electronic assembly and advanced packaging offerings can solve evolving industry challenges."

Kulicke & Soffa will be holding a technical seminar during the IPC APEX EXPO 2017 trade show on February 13, 2017, at Hotel del Coronado, San Diego.

Please contact your local sales and services representative for more information on K&S' comprehensive solutions and the seminar.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

View source version on [businesswire.com](http://www.businesswire.com): <http://www.businesswire.com/news/home/20170209005107/en/>

Kulicke & Soffa Industries, Inc.

Marilyn Sim
Public Relations
P: +65-6880-9309
F: +65-6880-9580
msim@kns.com

or

Kulicke & Soffa Industries, Inc.

Joseph Elgindy

Investor Relations & Strategic Initiatives

P: +1-215-784-7500

P: +31-40-272-3016

F: +1-215-784-6180

investor@kns.com

Source: Kulicke & Soffa Industries, Inc.

News Provided by Acquire Media